# Product Information Sheet

## EPO-TEK® 730 Black

| | | | |
|---|---|---|---|
| **Date:** | September 2017 | | **Recommended Cure: 80°C / 2 Hours** |
| **Rev:** | II | | |
| **No. of Components:** | Two | | Minimum Alternative Cure(s): |
| **Mix Ratio by Weight:** | 1 : 1 | | *May not achieve performance properties listed below* |
| **Specific Gravity:** | Part A: 1.12 | Part B: 0.94 | 100°C / 30 Minutes |
| **Pot Life:** | 1 Hour | | 23°C / 24 Hours |
| **Shelf Life- Bulk:** | One year at room temperature | | |

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

**Product Description:** A two component, room temperature curing, general and structural grade epoxy resin. It can be used for adhesive and sealing applications in medical, x-ray device, filtration, opto-electronics, and PCB industries. It is a thixotropic, black version of EPO-TEK® 730.

**Typical Properties:** Cure condition: 80°C / 2 Hours Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

| PHYSICAL PROPERTIES: | | |
|---|---|---|
| * Color (before cure): | Part A: Black | Part B: Tan |
| * Consistency: | Smooth paste | |
| * Viscosity (23°C) @ 2.5 rpm: | 80,000-120,000 | cPs |
| Thixotropic Index: | 2.1 | |
| * Glass Transition Temp: | ≥ 55 | °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min) |
| Coefficient of Thermal Expansion (CTE): | | |
| Below Tg: | 82 | x $10^{-6}$ in/in°C |
| Above Tg: | 245 | x $10^{-6}$ in/in°C |
| Shore D Hardness: | 64 | |
| Lap Shear @ 23°C: | > 2,000 | psi |
| Die Shear @ 23°C: | ≥ 10 | Kg 3,556 psi |
| Degradation Temp: | 364 | °C |
| Weight Loss: | | |
| @ 200°C: | 1.41 | % |
| @ 250°C: | 2.22 | % |
| @ 300°C: | 4.16 | % |
| Suggested Operating Temperature: | < 250 | °C (Intermittent) |
| Storage Modulus: | 110,458 | psi |
| * Particle Size: | ≤ 20 | microns |

| ELECTRICAL AND THERMAL PROPERTIES: | | |
|---|---|---|
| Thermal Conductivity: | N/A | |
| Volume Resistivity @ 23°C: | ≥ 1 x $10^{13}$ | Ohm-cm |
| Dielectric Constant (1KHz): | 3.50 | |
| Dissipation Factor (1KHz): | 0.024 | |

| OPTICAL PROPERTIES: | | |
|---|---|---|
| Spectral Transmission: | < 10% @ 480 | nm |
| | < 25% @ 980 | nm |
| | < 45% @ 1550 | nm |
| Refractive Index: | N/A | |



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